IPC ASSOCIATION CONNECT ELECTRONICS INDUSTR	Material Composi © Copyright 2005. IPC international and Pan-A	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowel level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mi	ials and Mfg Information				
Supplier Infor	mation															
Company name* Company unic				que ID U			Unique ID Authority					Response Date*				
nsemi													2025-06-08			
Contact Name		Title - Contact			1	Phone - Contact*					Email - Contact*					
Product-Env-Stev	wards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com					
uthorized Repres	Title - Representative			Phone - Representative*				Email - Representative*								
Product-Env-Stewards			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com						
Reques	ster Item Number	Mfr Item	m Number Mfr Item Name					e Date Version		Manufacturing Site		V	Veight [*]	*	UOM	Unit Type
		NCV8161AMX290TB XDFN4 AD G Noise and Hi		XDFN4 AD 2.9V Noise and High P			2025-06-08			THB		1	1.29		mg	Each
Ianufacturing	g Proccess Informatio	n														
Termina	al Plating / Grid Array Material		Terminal Base Alloy .		J-STD-020 MSL Rating		Peak Process Body Tempera		Body Temperatu	ure Max Time at Peak T		Temperati	nperature Number of Reflow Cycles		les	
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 1		1	260		С		30 seco		secono	ls 3			
Comments																
vel 1 - maximum	time at peak temperature	during sol	ldering is 10-3	0 seconds												
or more informa	tion regarding material co	nposition	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale appli											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.106	mg	Supplier	Silicon (Si)	7440-21-3		0.106	mg
Die Attach Tape	0.01	mg	Supplier	Oxirane, (chloromethyl)-, homopolymer	24969-06-0		0.0015	mg
			Supplier	2-Propenoic acid, 2-methyl-, polymer with butyl 2-propenoate and methyl 2-methyl-2-propenoate	25035-69-2		0.0015	mg
			Supplier	Proprietary	Proprietary Data		0.001	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.0045	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0015	mg
Lead Frame	0.78	mg	Supplier	Magnesium (Mg)	7439-95-4		0.0012	mg
			Supplier	Silicon (Si)	7440-21-3		0.0034	mg
			В	Nickel (Ni)	7440-02-0		0.0196	mg
			Supplier	Copper (Cu)	7440-50-8		0.7558	mg
Mold Compound-Black	0.35	mg		Epoxy resin	proprietary data		0.0164	mg
			Supplier	Phenol Resin	Proprietary Data		0.0164	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0004	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0.3167	mg
Plating	0.024	mg	Supplier	Palladium (Pd)	7440-05-3		0.0006	mg
			В	Nickel (Ni)	7440-02-0		0.0211	mg
			Supplier	Gold (Au)	7440-57-5		0.0023	mg
Wire Bond - Au	0.02	mg	Supplier	Gold (Au)	7440-57-5		0.02	mg